



### Description

The **DINO CONDENS-IT PROFILER** is designed for reflow soldering laboratory and prototype, single pieces and small quantities PCB'S. Components such as QFPs, BGAs, Flip-Chips as well as hybrids are processed defect free with highest quality results. Due the small footprint of the **DINO CONDENS-IT PROFILER** it may be used at any place. Its simple fast set up ensures a rapid ready for use providing the ability to solder high quality assemblies defect free.

### Features

- Table model Top loader
- **Adjustable temperature profiles in the pre-heating zone (CVPRS\*)**
- **Adjustable TAL Time Above Liquid**
- **ATS Anti Tomb Stone modus**
- **Micro USB for the transfer of solderprofile data to PC**
- Window to observe the soldering process
- Suitable for BGA's, Stacked Packages
- Oxygen Free Soldering
- Homogeneous temperature transmission on the complete Assembly
- No over heating of components

**\*Creative Vapor Phase Reflow Software**

<b>DINO CONDENS IT PROFILER</b>		<b>Order No.</b>	<b>Price</b>
<b>IMDES</b> Vapor Phase soldering machine <b>DINO CONDENS IT PROFILER</b> excluding transfer medium		<b>IMD-DINO-1 Prof</b>	
Medium basic filling Galden LS230 Reflow Fluid for lead free applications Quantity 1,923 Liter = 3,5 Kg		<b>IMD-GL 230-3.5 Kg</b>	
Energy supply (Single Phase + ground)	220-240 Volt / 50-60 Hz		
Power drawn	2500 Watt (ca. 12 A)		
System dimensions.	840 x 640 x 460 mm (L x W x H)		
max. solder product format	<b>580 x 460 x 20 mm</b> (L x B x H)		
Standard cycle time	15 –25 Min		
Soldering time	ca. 60 – 90 Seconds		
Process temperature (depends on medium type)	150 up to 240 °C		
Weight	ca. 25 kg		
Cooling	Forced air cooling		
Heat transfer medium	GALDEN with the correct boiling temperature (max. 240 °C) higher Temperature is not possible		
Medium basic filling quantity	ca. 1648 ml (1.65 Liter) 3 Kg GALDEN		